

AMENDMENT TO THE CLAIMS

Claims 1-21 (Cancelled)

22.**(New)** A plating apparatus, comprising:

a plating tank for holding a plating solution;

a holder for holding a workpiece and bringing a surface to be plated of the workpiece into contact with the plating solution in the plating tank; and

a ring-shaped nozzle pipe disposed in the plating tank and having a plurality of plating solution injection nozzles for injecting the plating solution toward the surface to be plated of the workpiece held by the holder to supply the plating solution into the plating tank.

23.**(NEW)** A plating apparatus according to claim 22, wherein streams of the plating solution injected from the plating solution injection nozzles join each other on or in front of a substantially central area of the surface to be plated of the workpiece held by the holder.

24. **(NEW)** A plating apparatus according to claim 22, wherein the plating apparatus comprises an electroplating apparatus having an anode, and a plating voltage is applied between the anode and the workpiece to perform electroplating on the workpiece.

25. **(NEW)** A plating apparatus according to claim 24, further comprising a plating solution injection nozzle for injecting the plating solution toward the anode to supply the plating solution into the plating tank.

26. **(NEW)** A plating apparatus according to claim 22, wherein the plating apparatus comprises an electroless plating apparatus for bringing an electroless plating solution into contact with the surface to be plated of the workpiece to perform electroless plating on the workpiece.

27. **(NEW)** A plating apparatus according to claim 22, wherein the workpiece is disposed horizontally.

28. **(NEW)** A plating apparatus according to claim 22, wherein the workpiece is disposed vertically.

29. **(NEW)** A plating apparatus according to claim 22, wherein the nozzle pipe is shaped to extend along an outer profile of the workpiece.

30. **(NEW)** A plating apparatus according to claim 22, wherein the nozzle pipe is movable relatively to the workpiece held by the holder.

31. **(NEW)** A plating apparatus according to claim 22, wherein the nozzle pipe and/or the plating solution injection nozzles are made of an electrically insulating material.

32.**(NEW)** A plating apparatus, comprising:

a plating tank for holding a plating solution; and

a stirring mechanism having a stirring vane immersed in the plating solution in the plating tank and disposed in a position facing a surface to be plated of a workpiece, the stirring vane being reciprocally movable parallel to the surface to be plated of the workpiece to stir the plating solution;

wherein the stirring vane has irregularities on at least one side thereof, the irregularities comprise a succession of triangular or rectangular saw-tooth irregularities, or a number of narrow grooves defined at predetermined intervals.

33.**(NEW)** A plating apparatus according to claim 32, wherein the side of the stirring vane with the irregularities provided thereon faces the surface to be plated of the workpiece.

34. **(NEW)** A plating apparatus according to claim 32, wherein the stirring mechanism has a plurality of the stirring vanes.

35. **(NEW)** A plating apparatus, comprising:

a plating tank for holding a plating solution; and

a stirring mechanism having a stirring vane immersed in the plating solution in the plating tank for stirring the plating solution;

wherein the stirring vane comprises a plurality of stirring vanes which are actuatable by respective independent drive mechanisms.

36. **(NEW)** A plating apparatus according to claim 35, wherein the stirring vanes are different in shape from each other.

37. **(NEW)** A plating apparatus according to claim 35, wherein the stirring vanes are reciprocally movable in directions parallel to a surface to be plated of a workpiece.

38. **(NEW)** A plating apparatus, comprising:

a plating tank for holding a plating solution; and

a stirring mechanism having a stirring vane immersed in the plating solution in the plating tank and disposed in a position facing a surface to be

plated of a workpiece, the stirring vane being reciprocally movable parallel to the surface to be plated of the workpiece to stir the plating solution;

wherein the stirring vane has an angle with respect to the surface to be plated of the workpiece, the angle being variable as the direction in which the stirring vane moves is changed.

39. **(NEW)** A plating apparatus according to claim 38, wherein the stirring mechanism has a plurality of the stirring vanes.